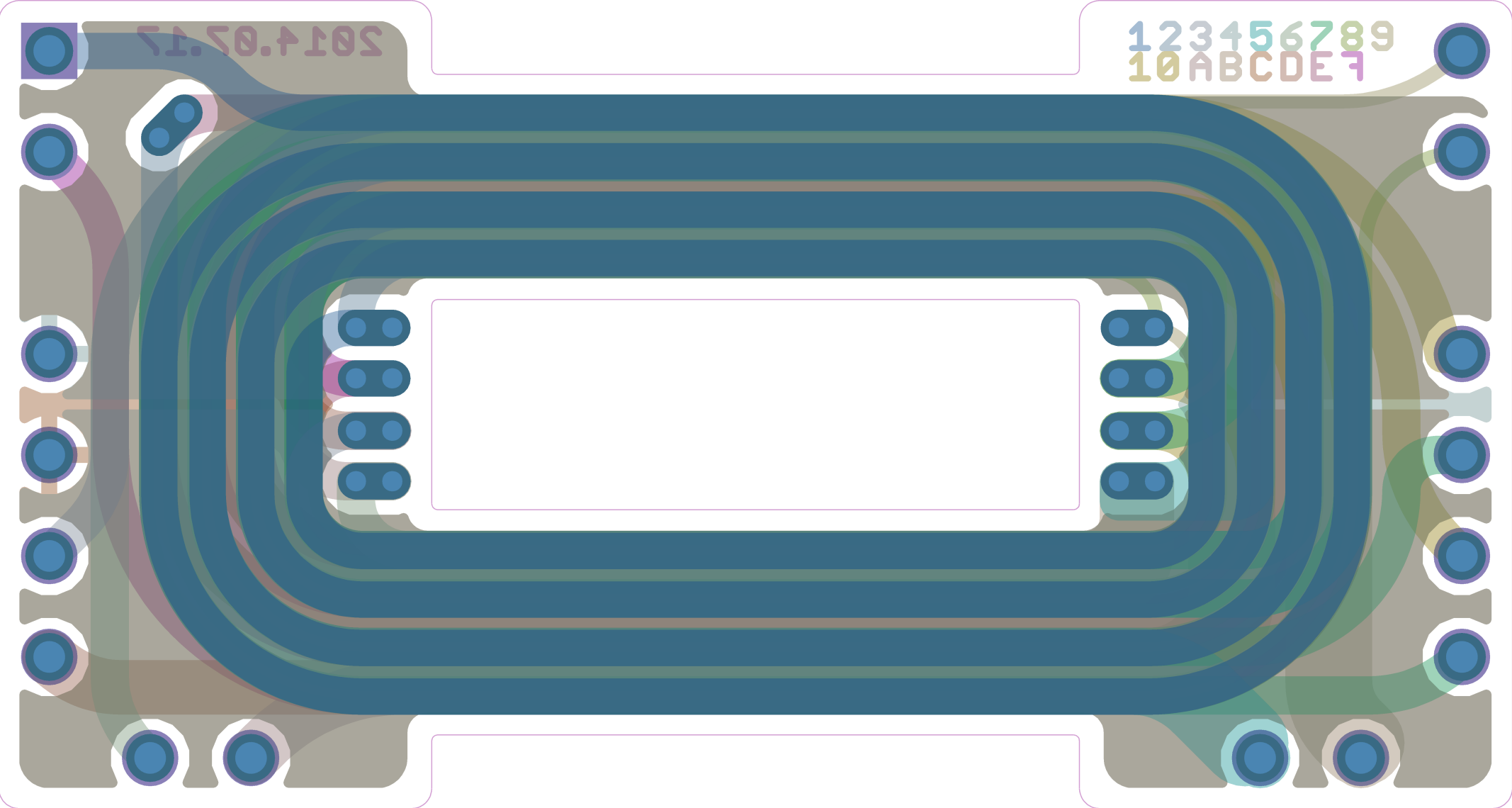
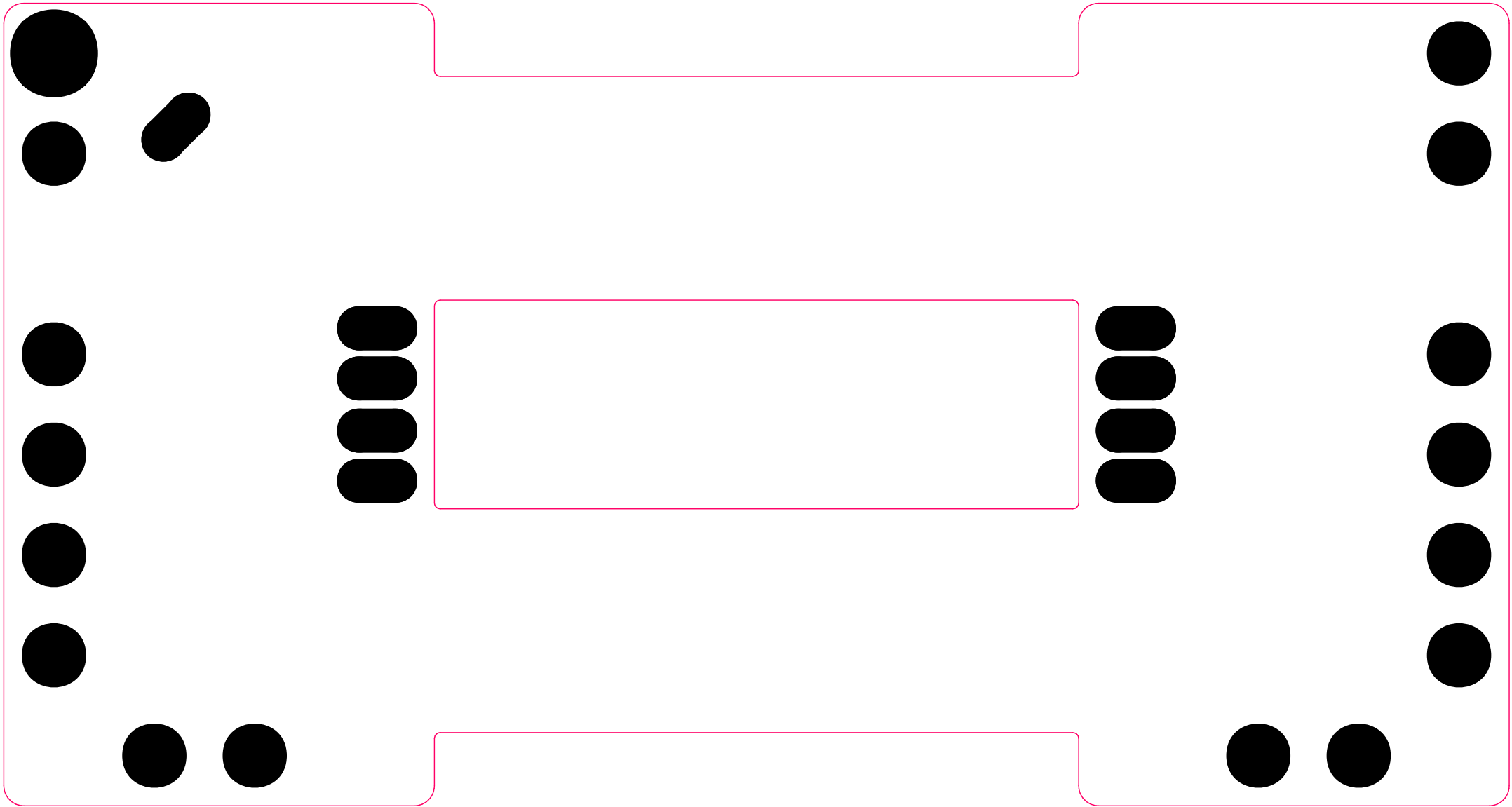
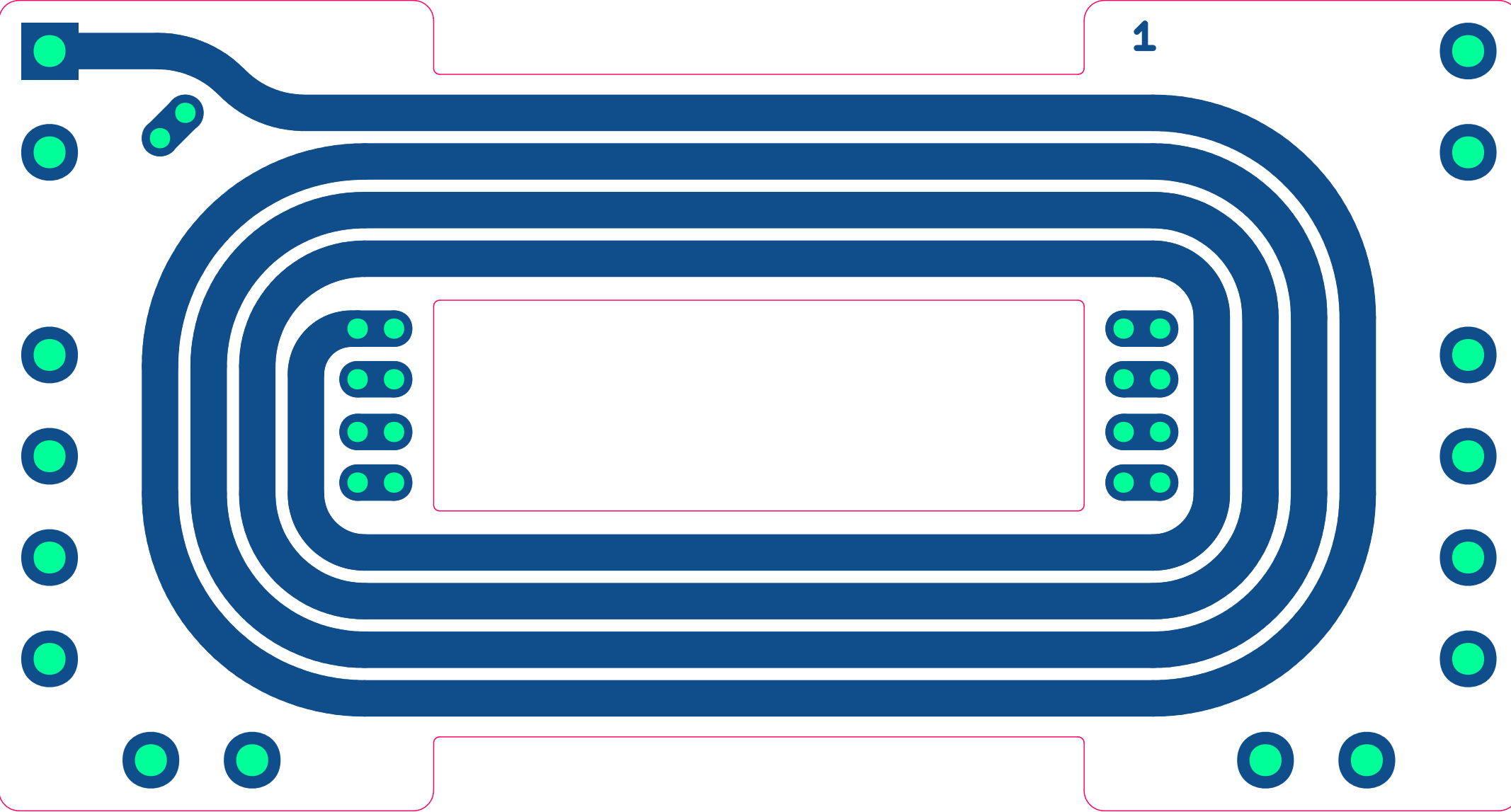
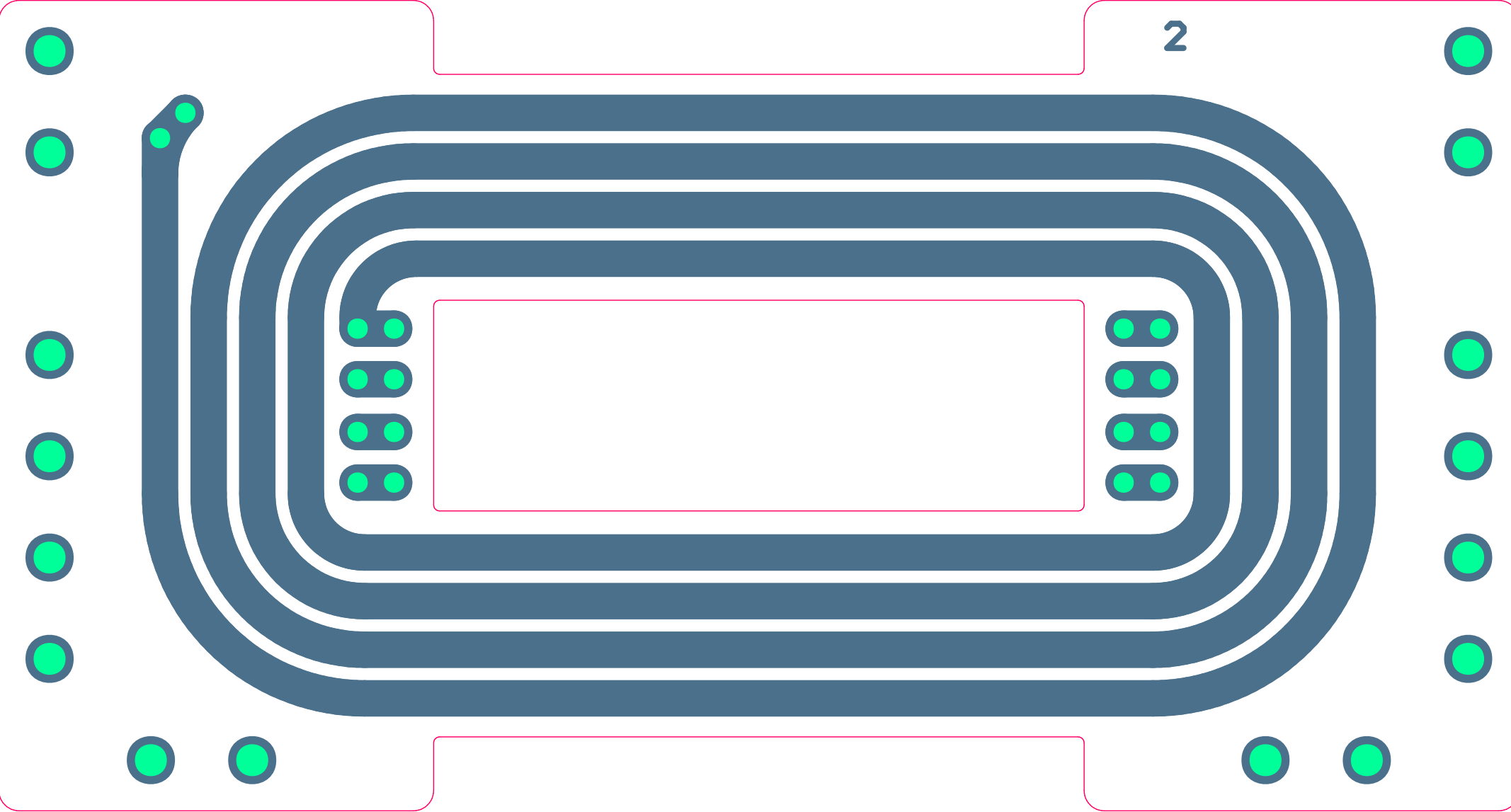
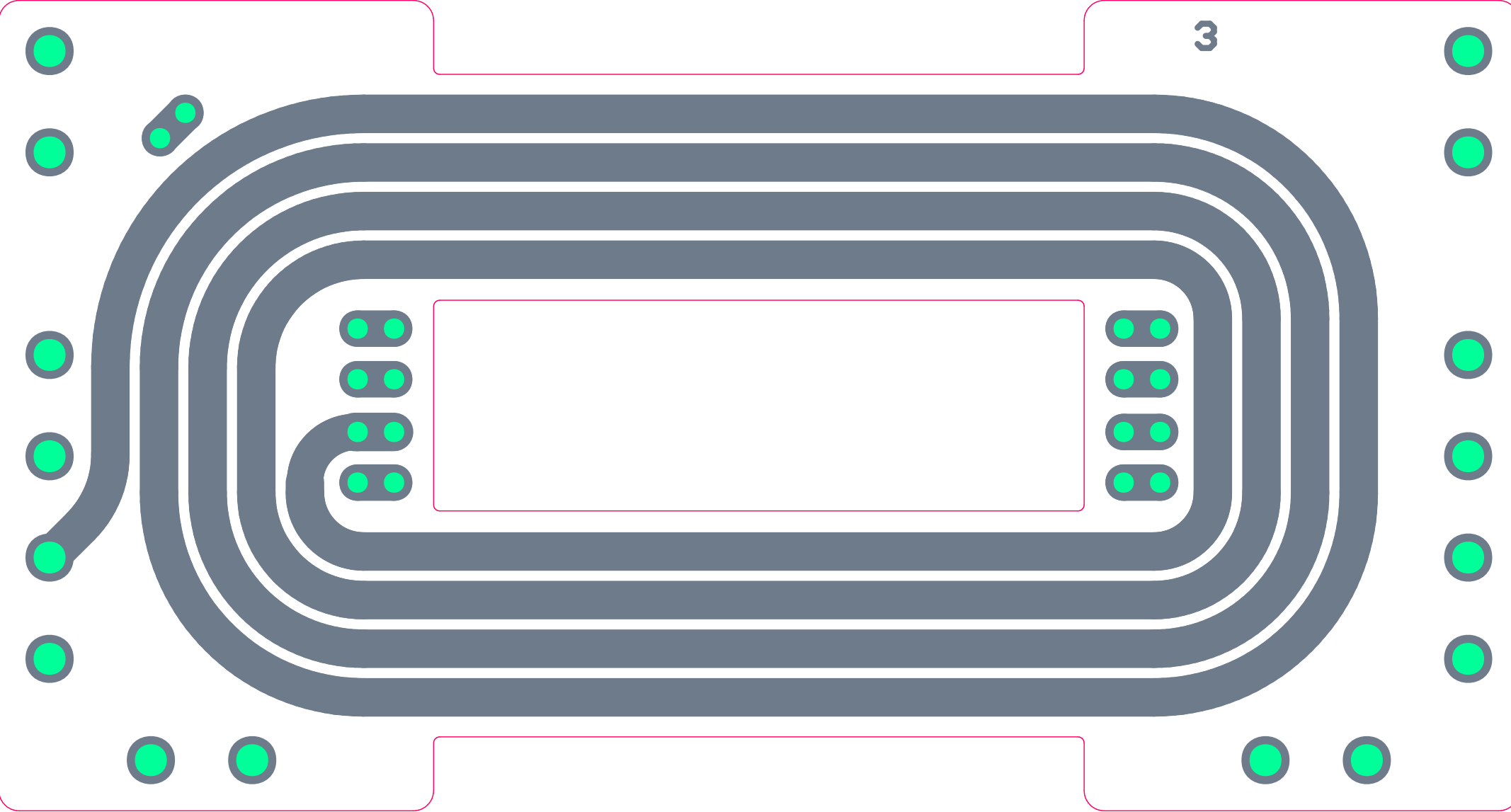


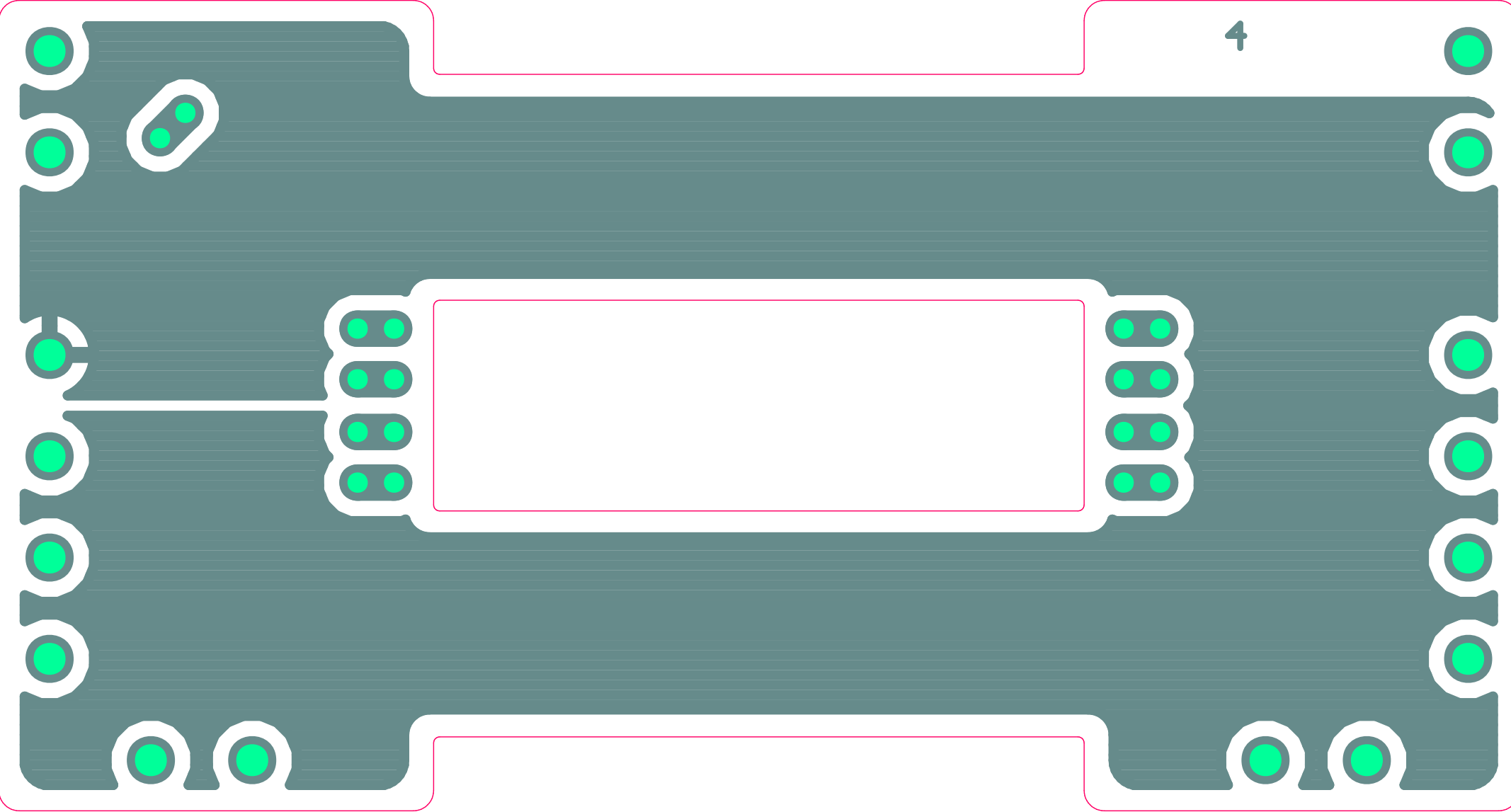




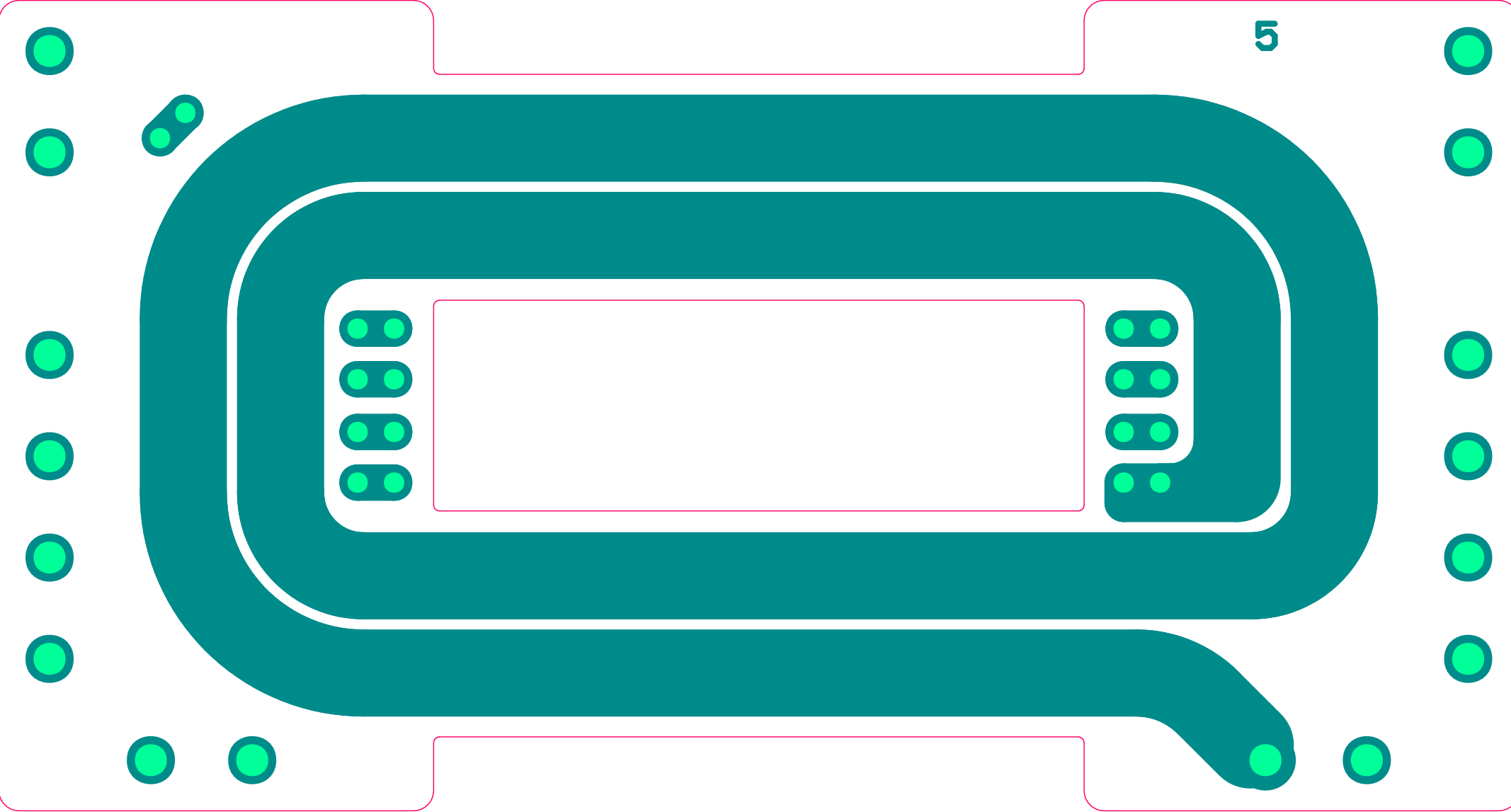




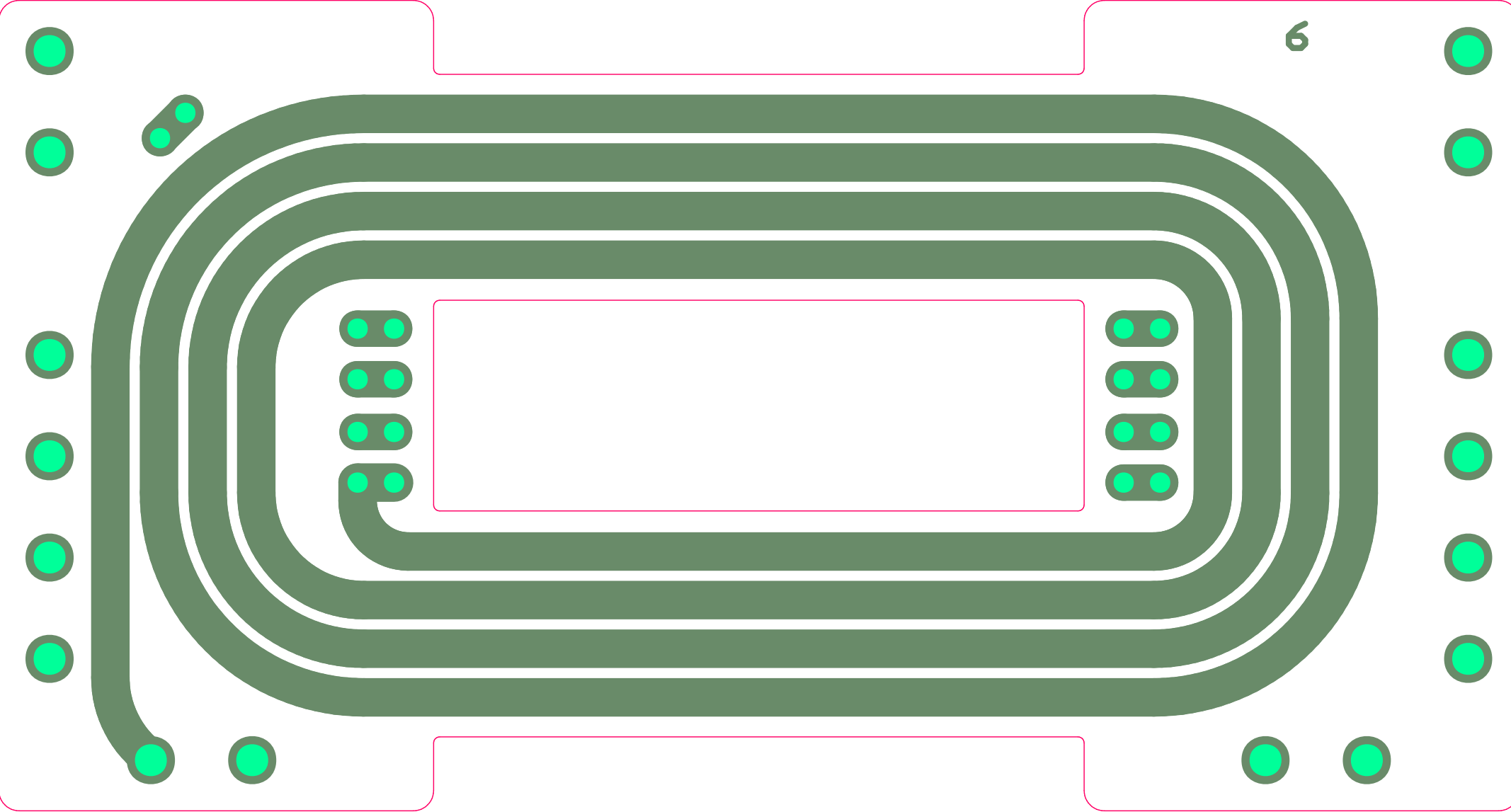


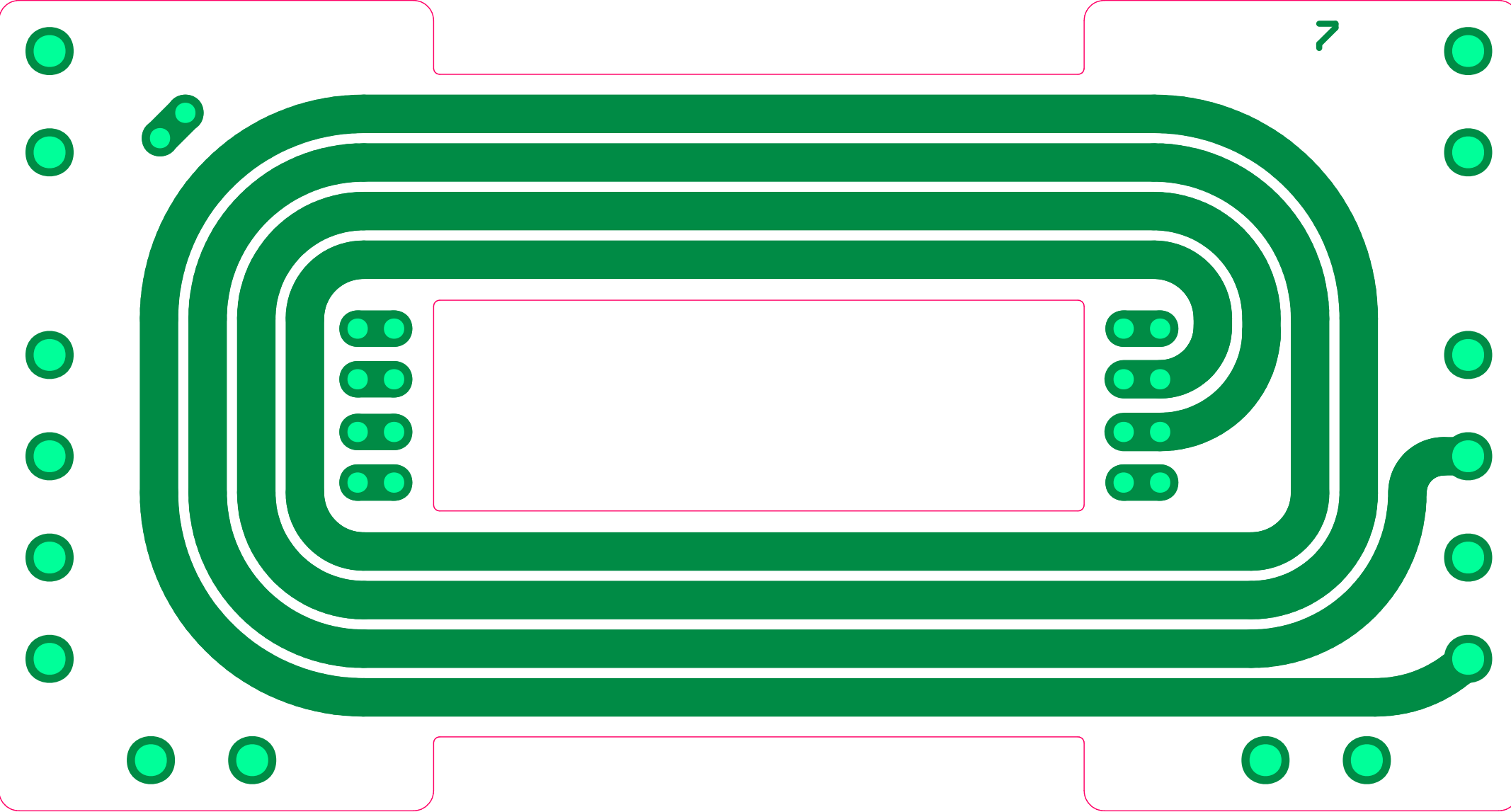


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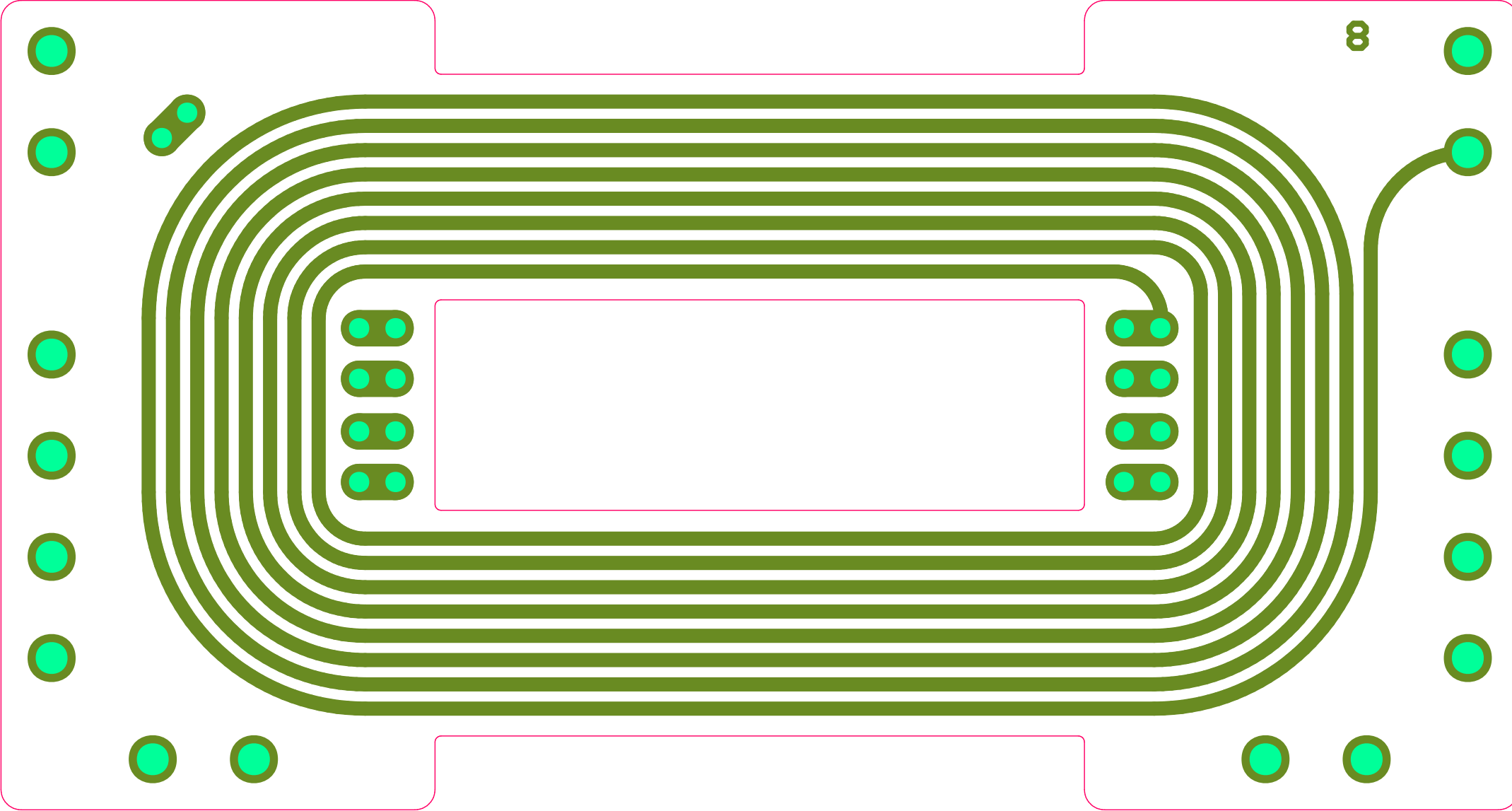


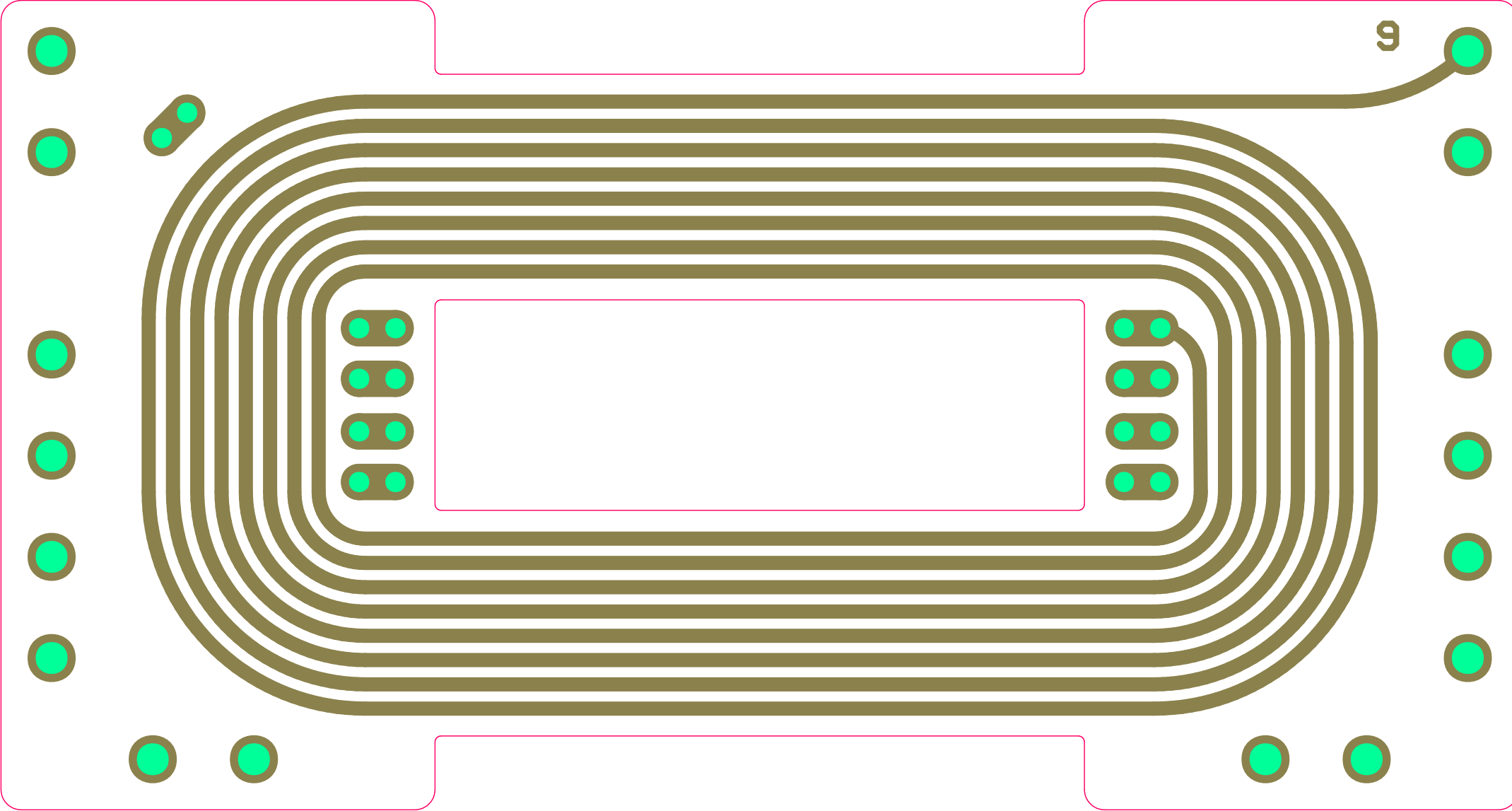
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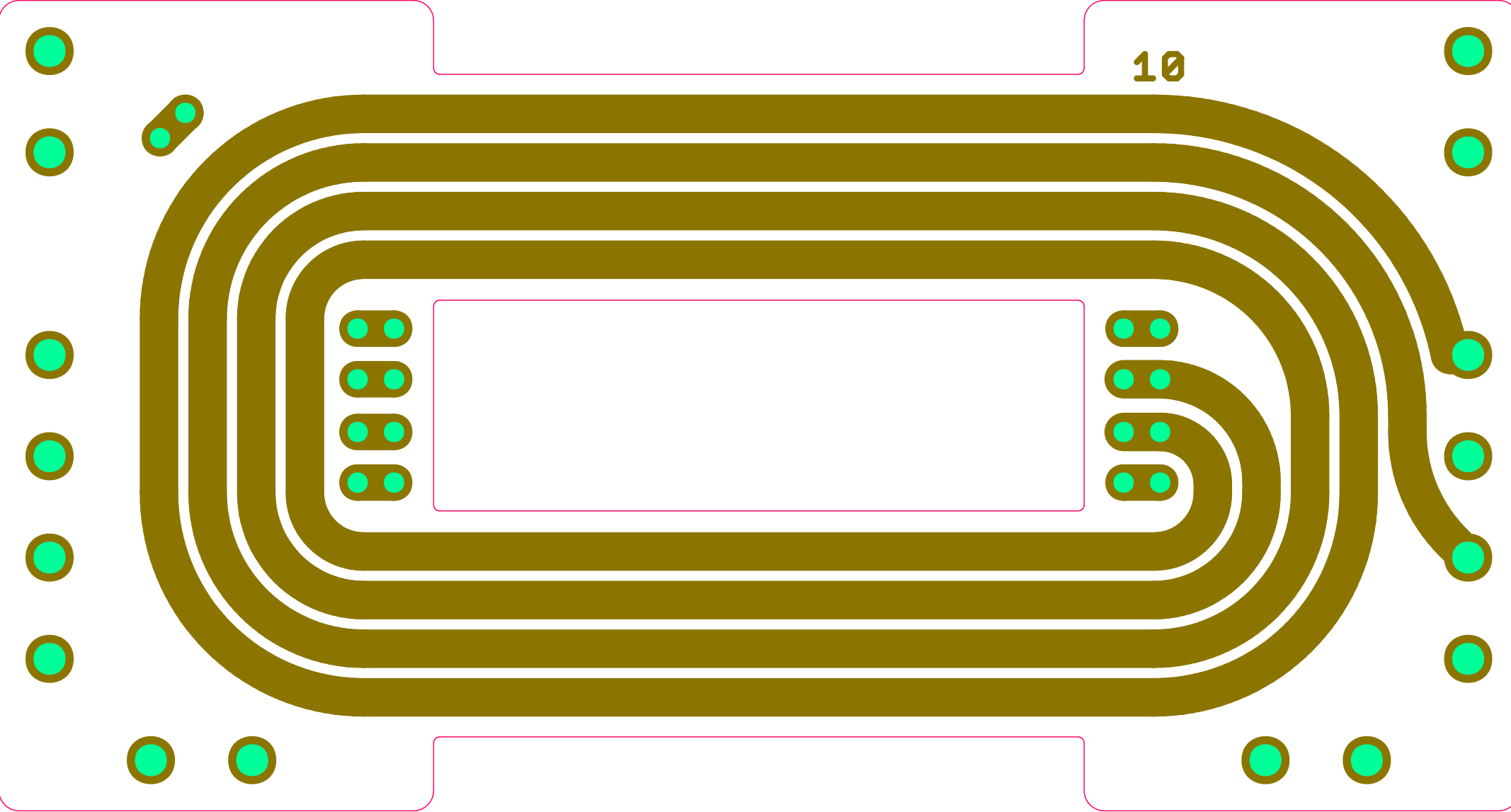


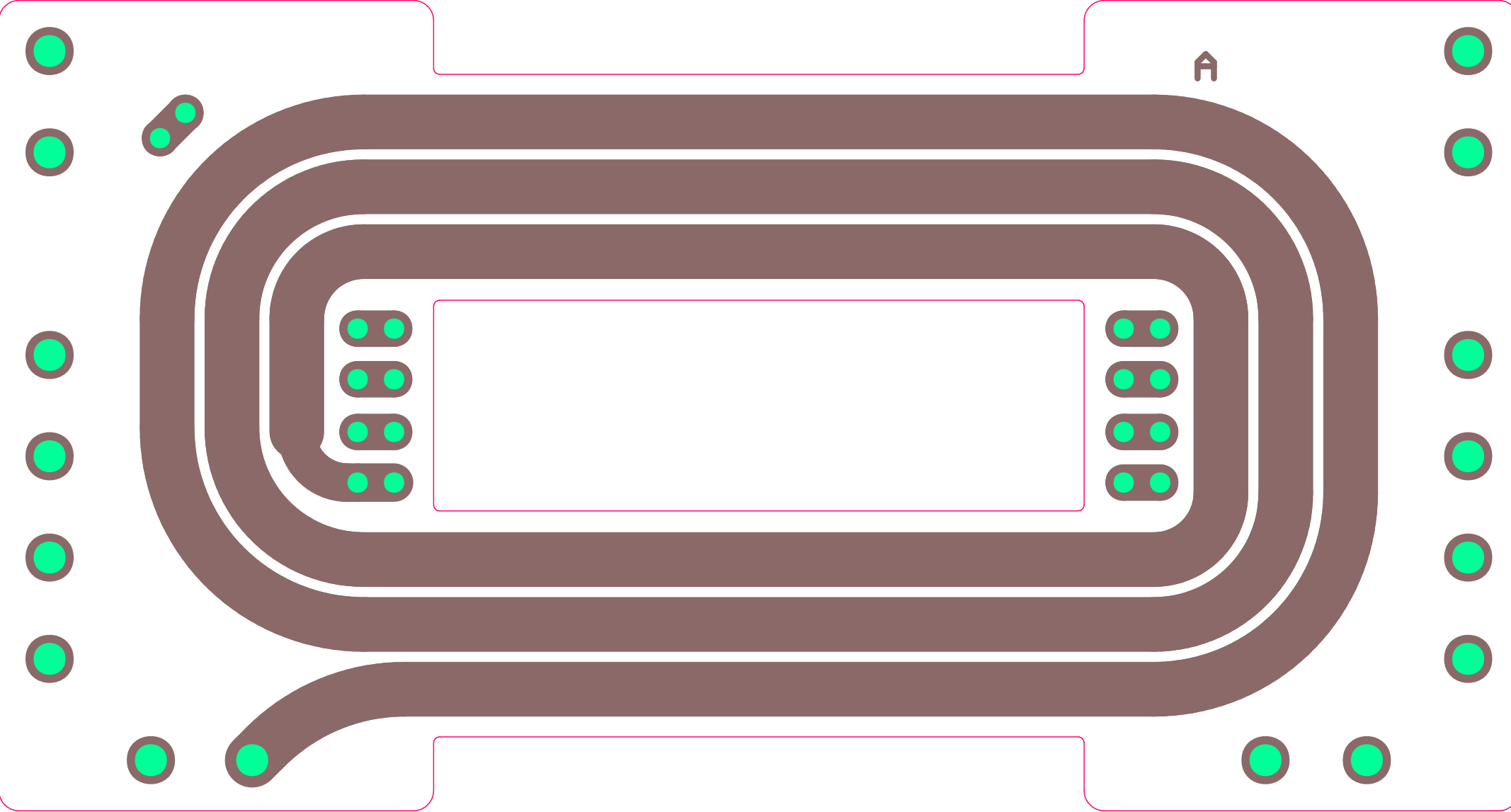


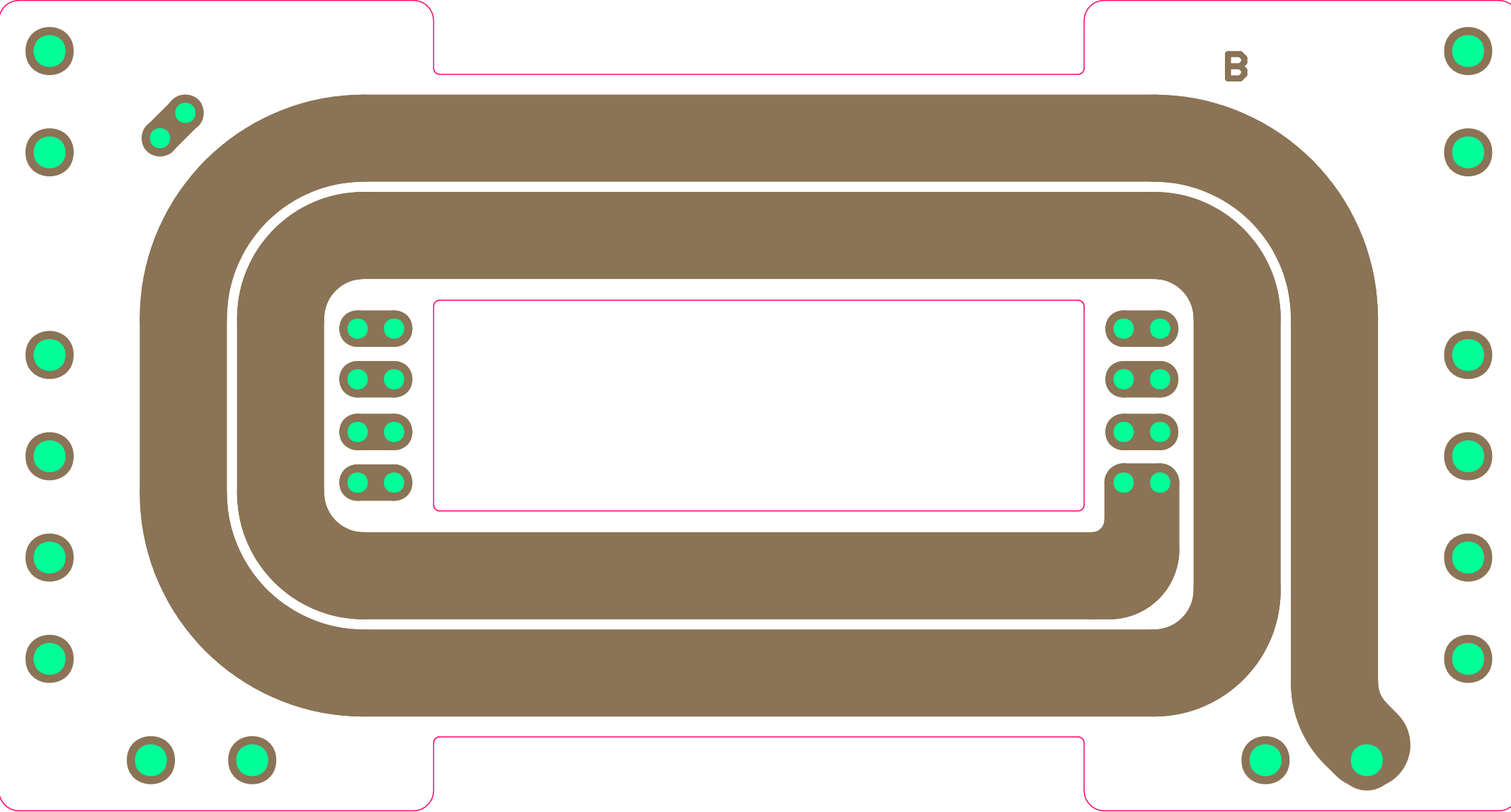
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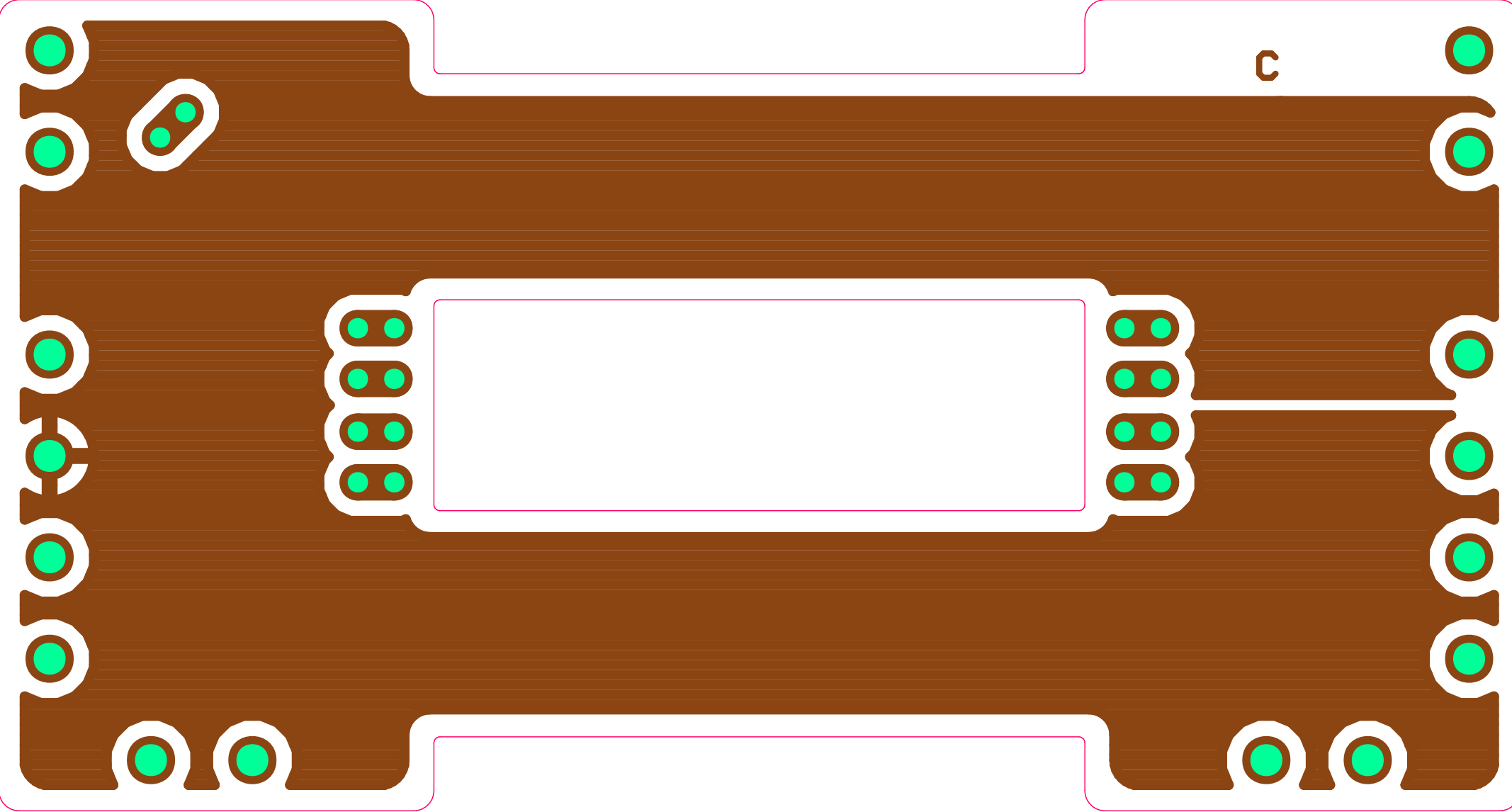


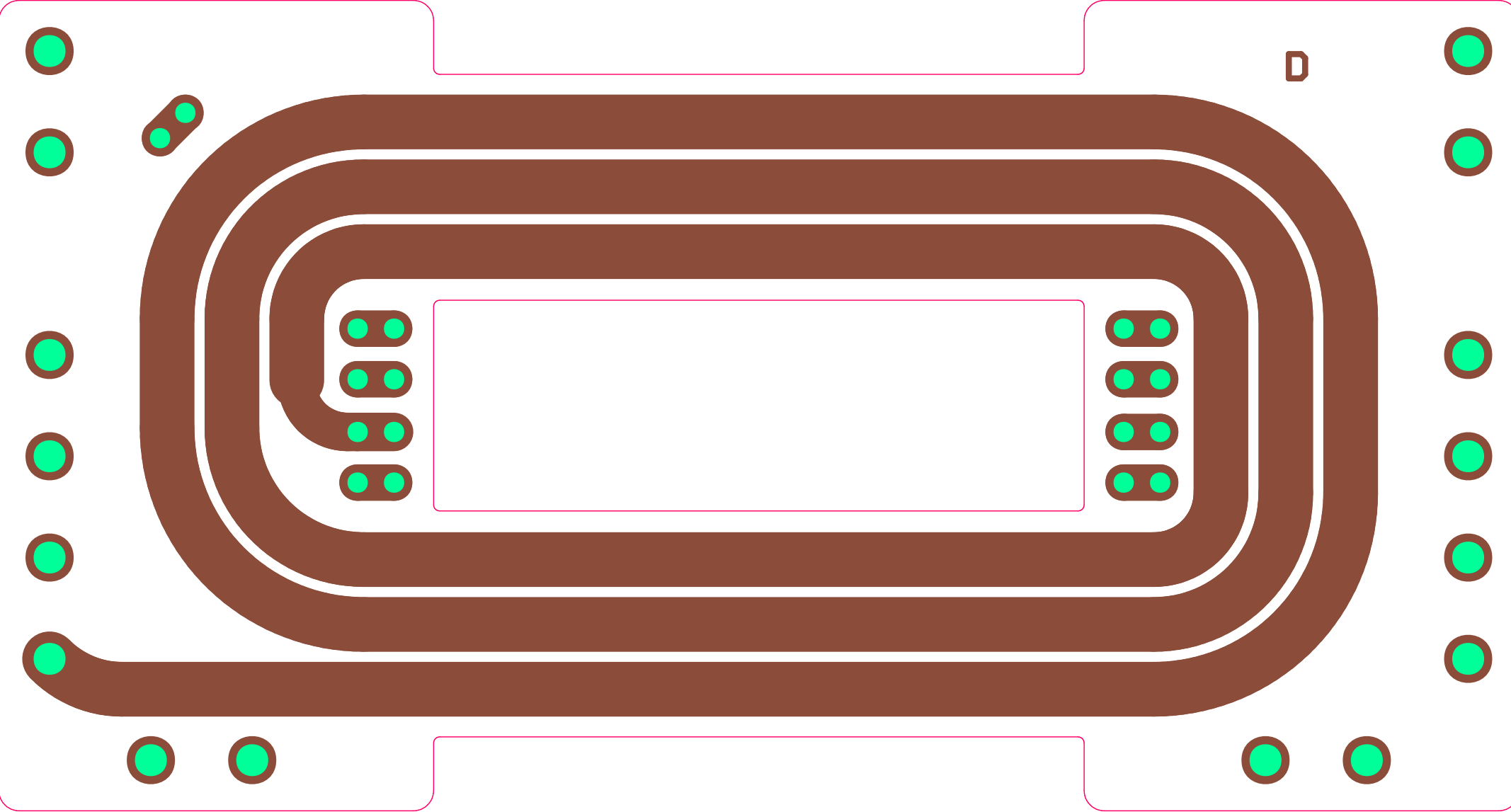


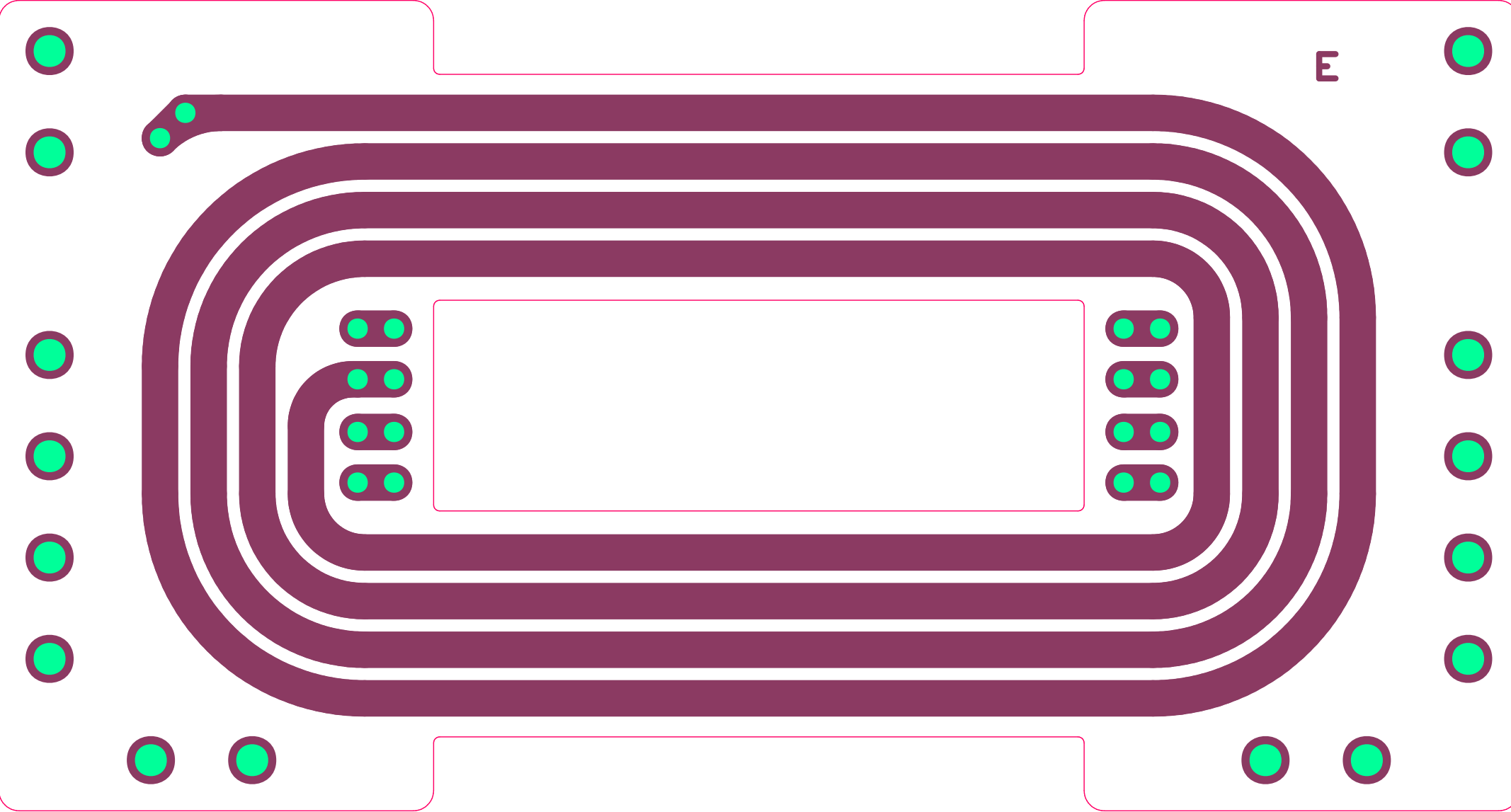


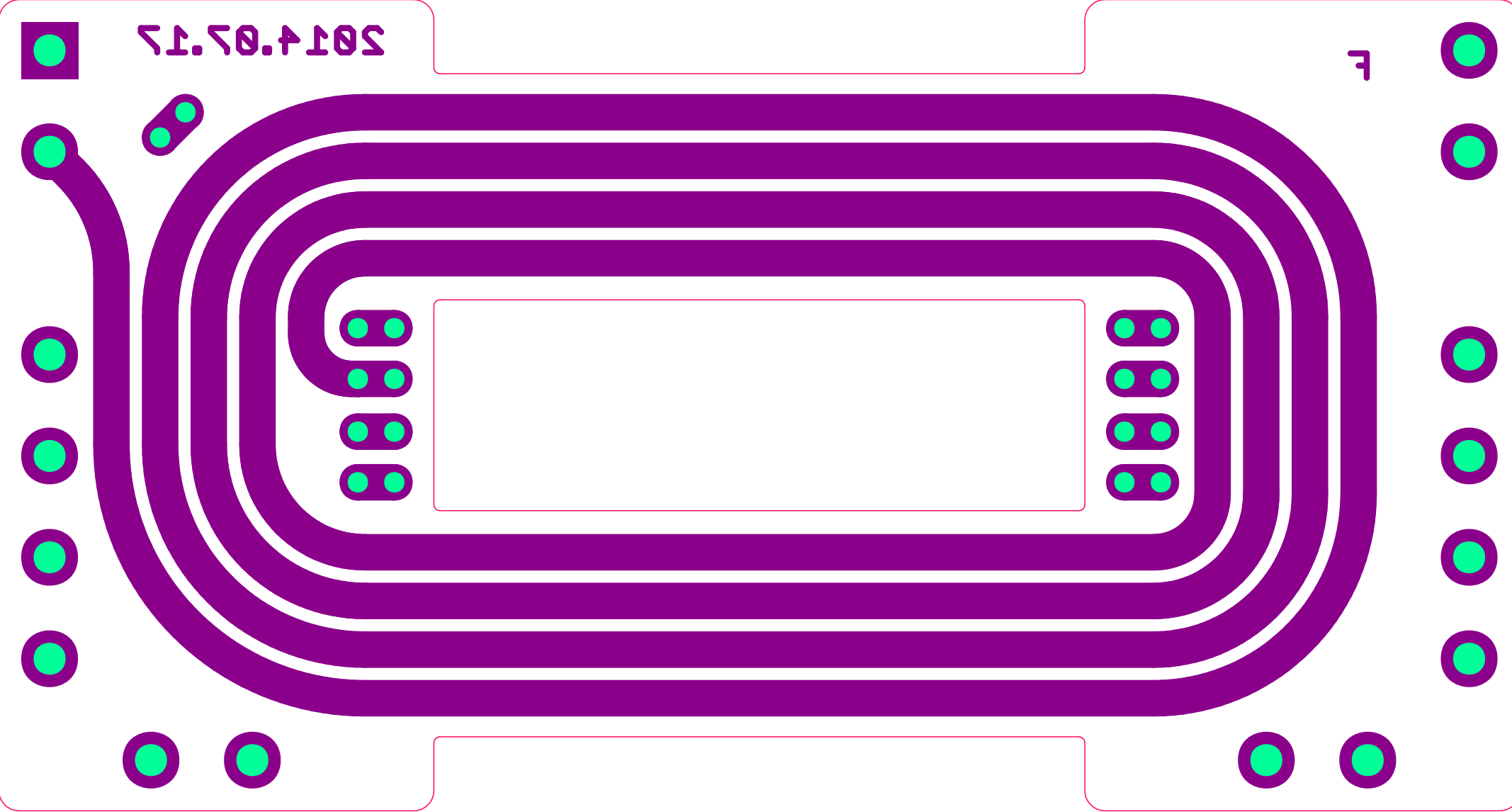


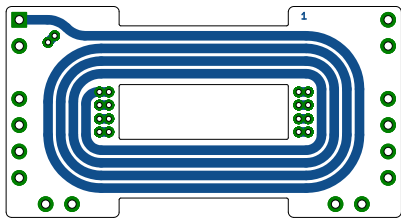




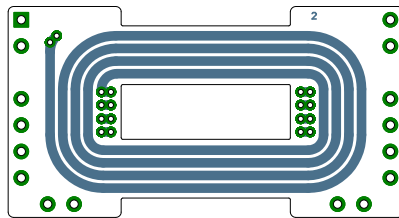




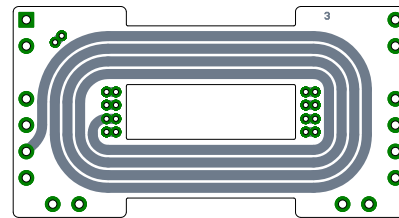




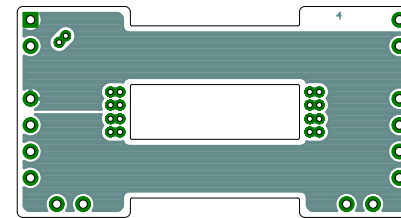
PRIM 1 of 4



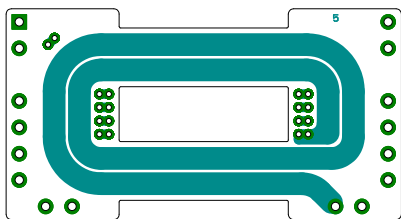
PRIM 2 of 4



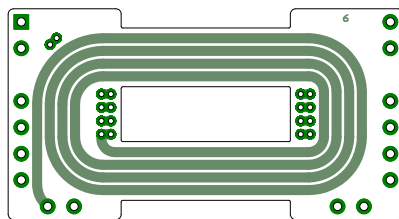
12V_SEC 1 of 2



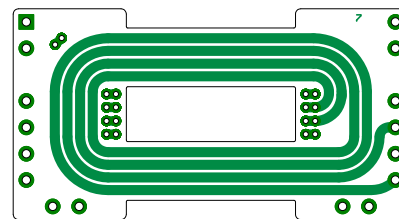
SHIELD Layer 4



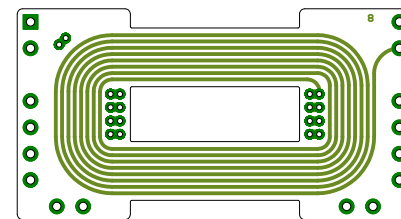
DIG 1 of 2



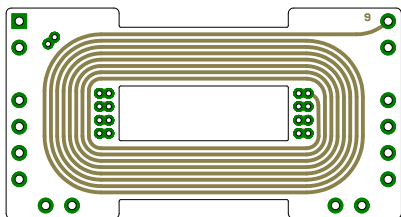
HEATER 1 of 2



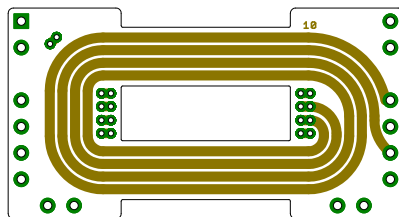
ANA 1 of 2



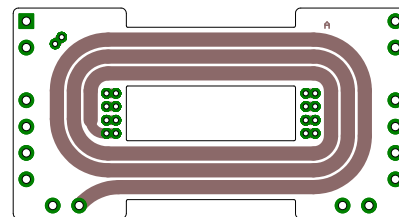
BIAS 1 of 2



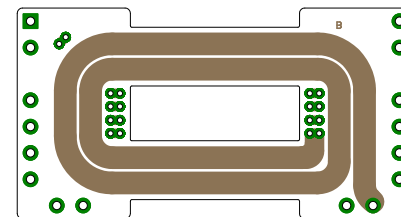
BIAS 2 of 2



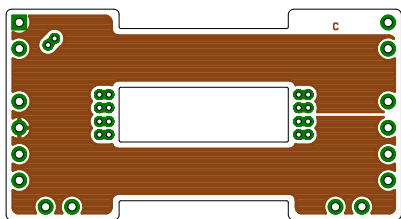
ANA 2 of 2



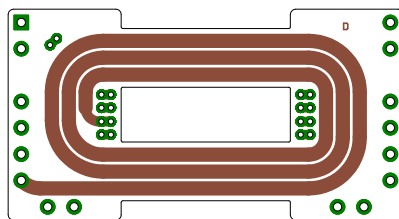
HEATER 2 of 2



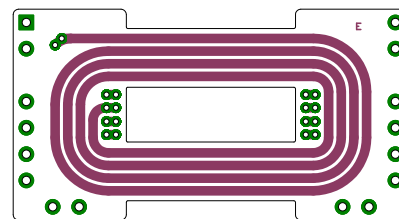
DIG 2 of 2



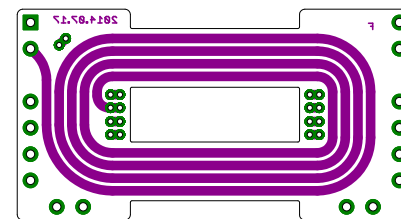
SHIELD Layer 13



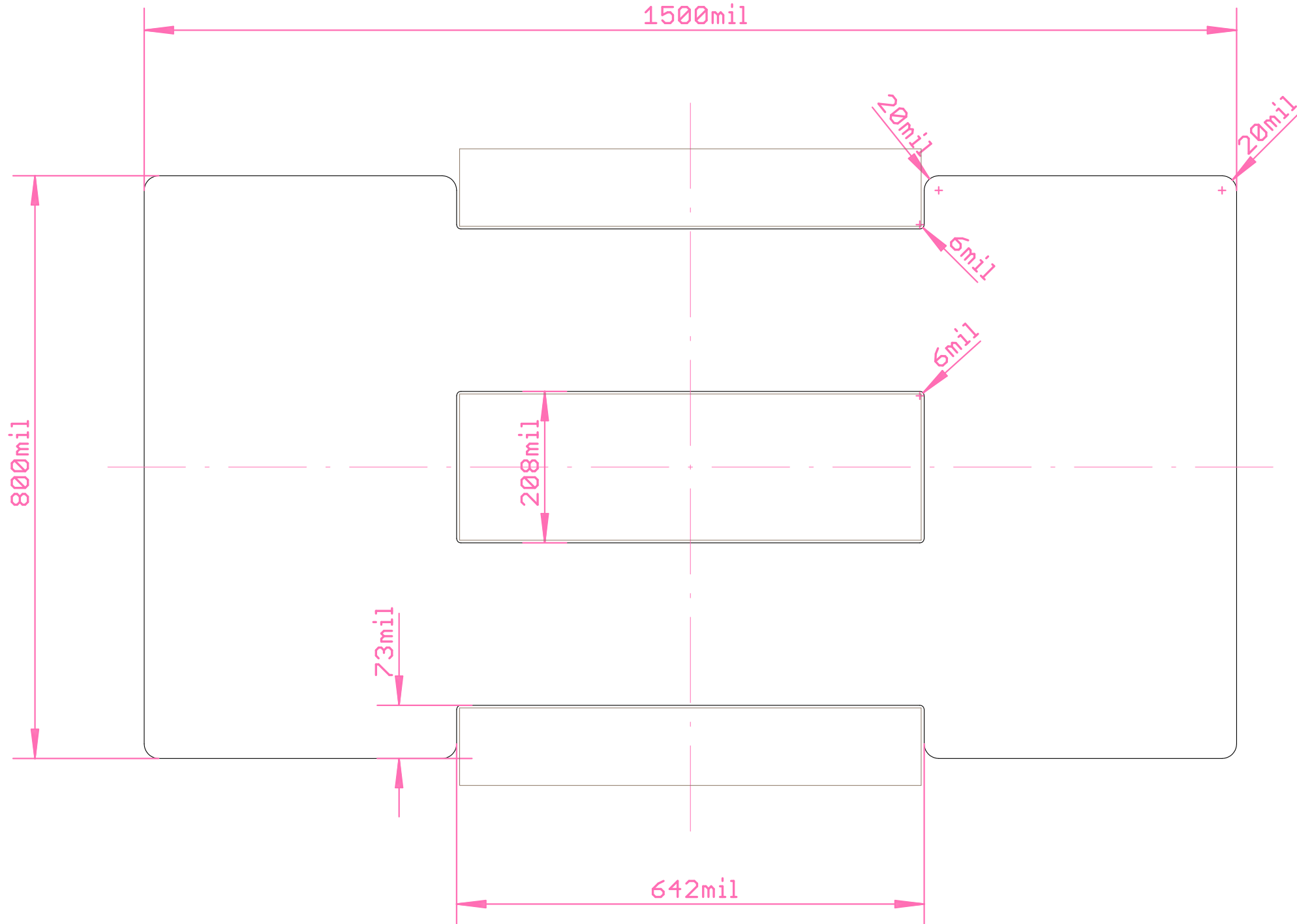
12V_SEC 2 of 2



PRIM 3 of 4



PRIM 4 of 4



planartrafo-layerstack

Layer	Signal Name	Name	Layer	Thickness / μm
		cover foil, 50 μm acrylic glue & 25 μm polyimide foil	Cover Foil	50
1	PRIM 1 of 4	Copper 70 μm	Copper	70
		2 x 106 + 1 x 1080 polyimide prepreg	Prepreg	135
2	PRIM 2 of 4	Copper 70 μm	Copper	70
		polyimide laminate 100 μm	Laminate	100
3	12V_SEC_ON_PRIM 1 of 2	Copper 70 μm	Copper	70
		2 x 106 + 1 x 1080 polyimide prepreg	Prepreg *	135
4	SHIELD Layer 4	Copper 70 μm	Copper	70
		polyimide laminate 100 μm	Laminate	100
5	DIG 1 of 2	Copper 70 μm	Copper	70
		2 x 106 + 1 x 1080 polyimide prepreg	Prepreg	100
6	12V_HEATER 1 of 2	Copper 70 μm	Copper	70
		polyimide laminate 100 μm	Laminate	100
7	ANA+ ANA- 1 of 2	Copper 70 μm	Copper	70
		2 x 106 + 1 x 1080 polyimide prepreg	Prepreg	100
8	BIAS 1 of 2	Copper 70 μm	Copper	70
		polyimide laminate 100 μm	Laminate	100
9	BIAS 2 of 2	Copper 70 μm	Copper	70
		2 x 106 + 1 x 1080 polyimide prepreg	Prepreg	100
10	ANA+ ANA- 2 of 2	Copper 70 μm	Copper	70
		polyimide laminate 100 μm	Laminate	100
11	12V_HEATER 2 of 2	Copper 70 μm	Copper	70
		2 x 106 + 1 x 1080 polyimide prepreg	Prepreg	100
12	DIG 2 of 2	Copper 70 μm	Copper	70
		polyimide laminate 100 μm	Laminate	100
13	SHIELD Layer 13	Copper 70 μm	Copper	70
		2 x 106 + 1 x 1080 polyimide prepreg	Prepreg *	135
14	12V_SEC_ON_PRIM 2 of 2	Copper 70 μm	Copper	70
		polyimide laminate 100 μm	Laminate	100
15	PRIM 3 of 4	Copper 70 μm	Copper	70
		2 x 106 + 1 x 1080 polyimide prepreg	Prepreg	135
16	PRIM 4 of 4	Copper 70 μm	Copper	70
		cover foil, 50 μm acrylic glue & 25 μm polyimide foil	Cover Foil	50
Thickness total				2860

Absolute Maximum PCB Thickness 3.00mm

* Copperarea of Shieldlayer is > 67%, this results in a thicker prepreg than the other layers